

FIG. 1A

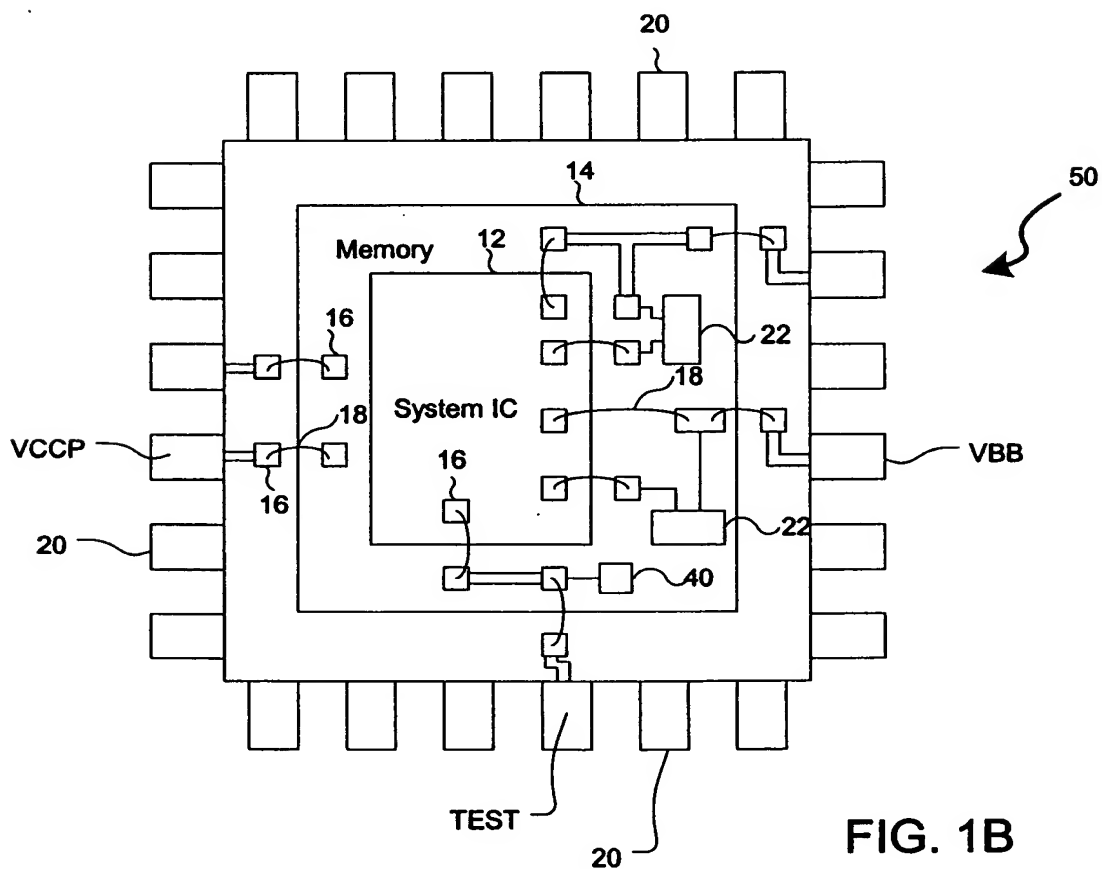
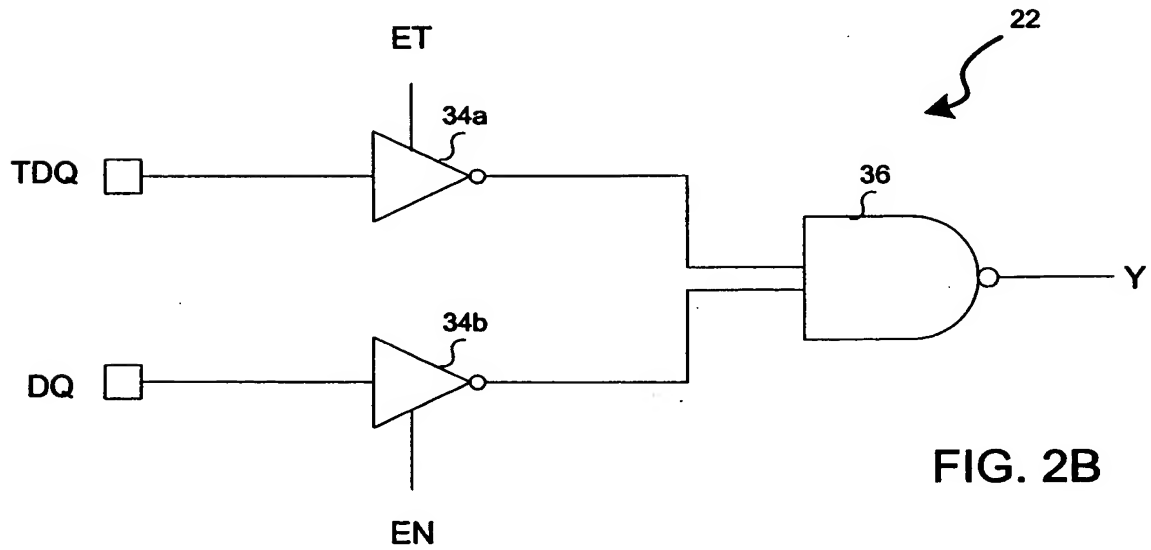
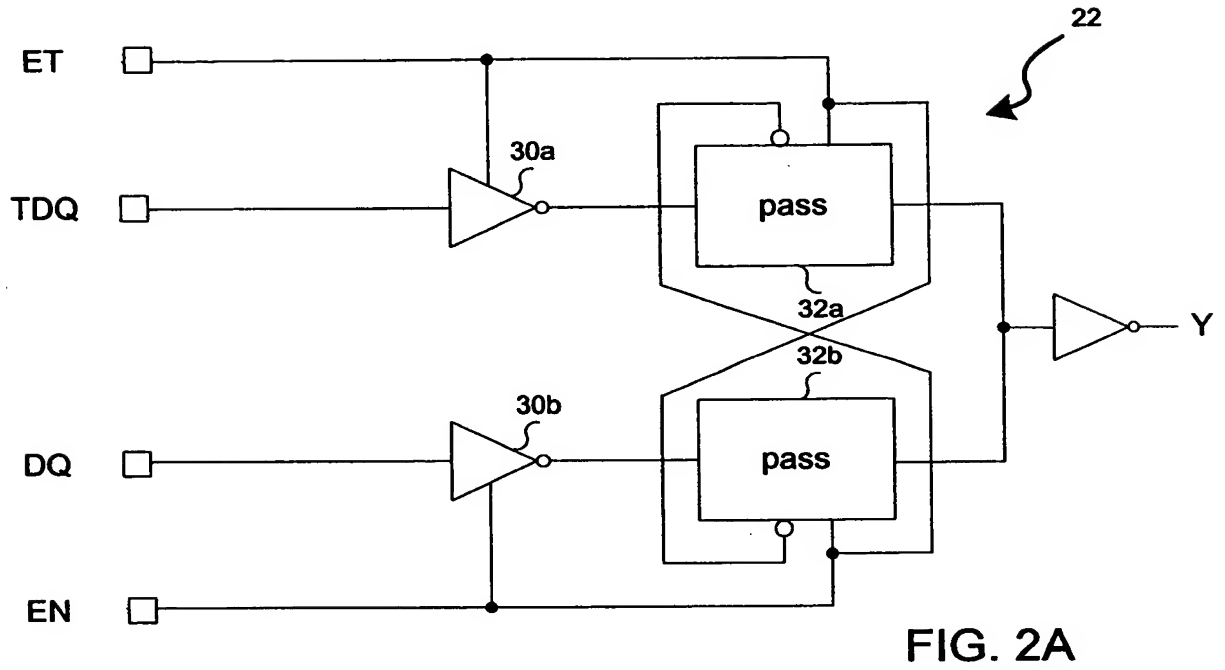


FIG. 1B



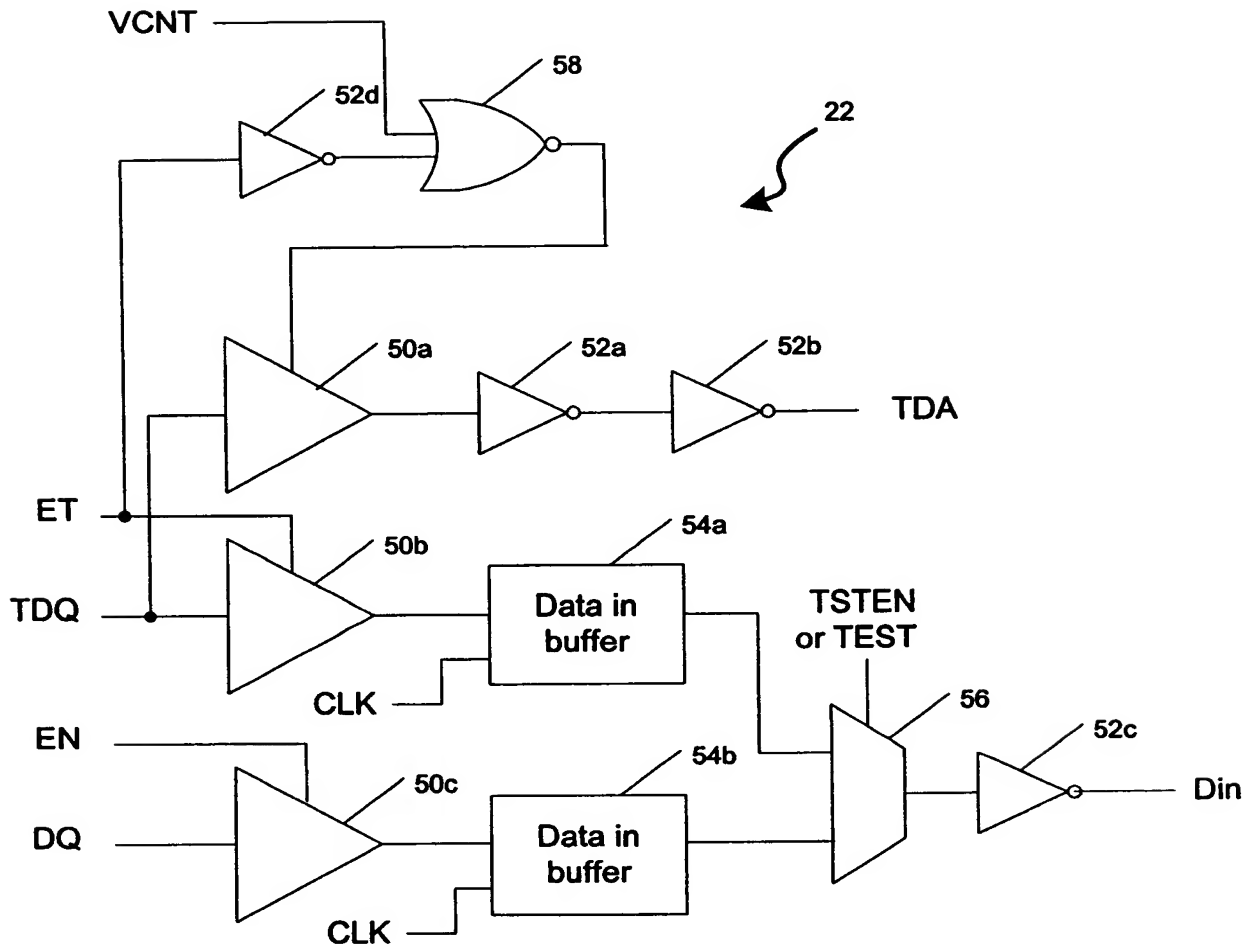


FIG. 2C

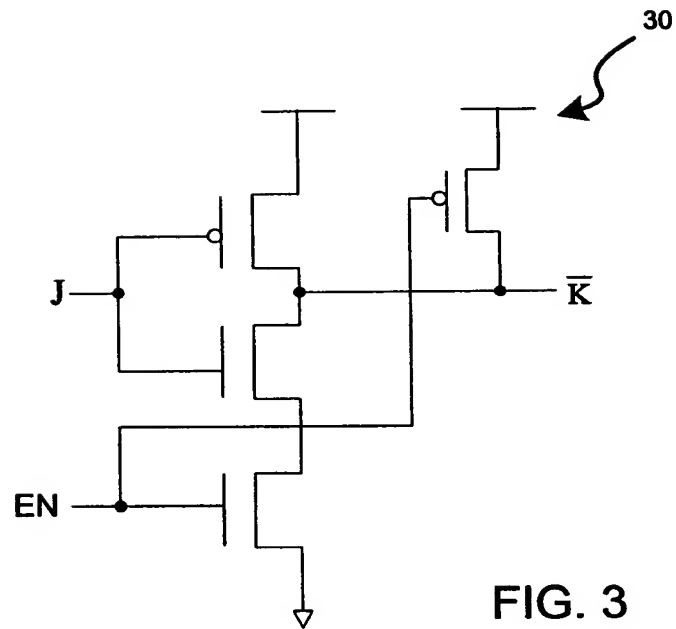


FIG. 3

The diagram shows a circuit labeled 42. It starts with an input signal XTEST, represented by a square wave. This signal passes through a series of three inverters. After the third inverter, the signal line branches: one path goes through a transistor connected to ground, and the other path goes through a feedback loop consisting of two more inverters. The output of the second inverter in the feedback loop is labeled TSTEN. A curved arrow labeled 42 points to the feedback loop.

FIG. 5

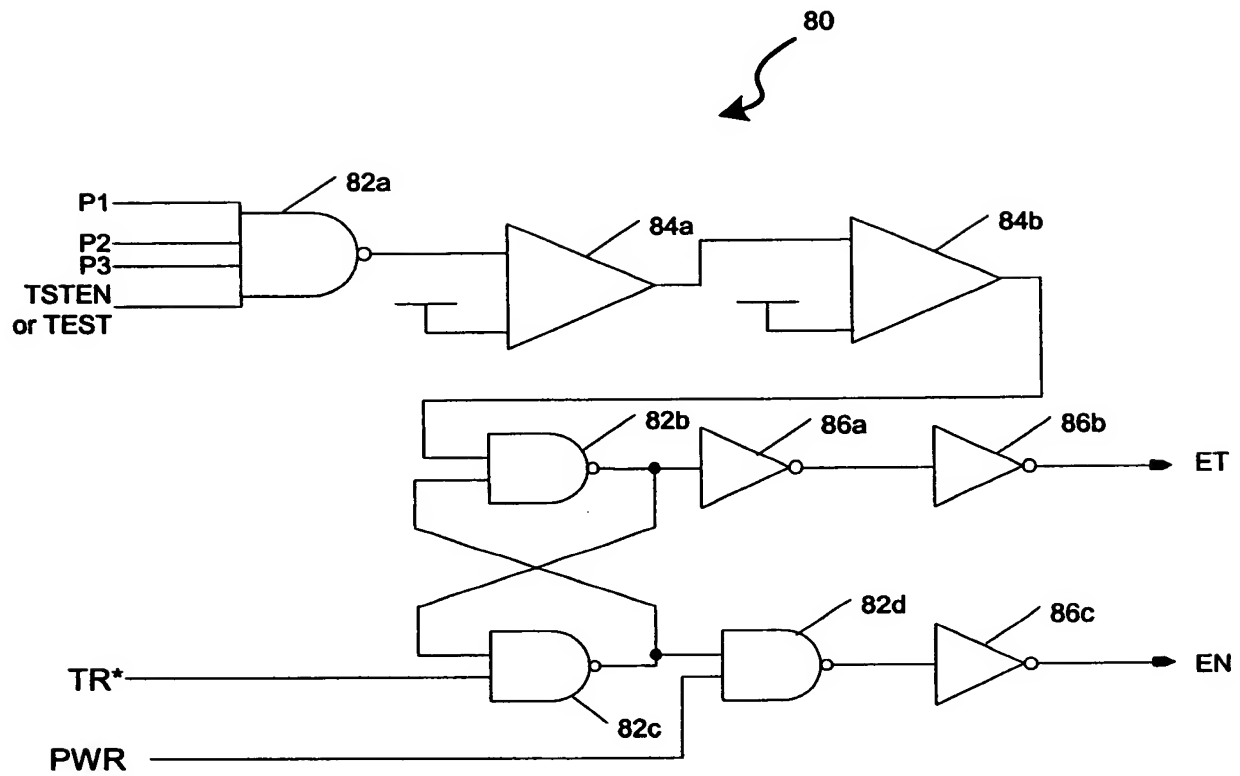


FIG. 6

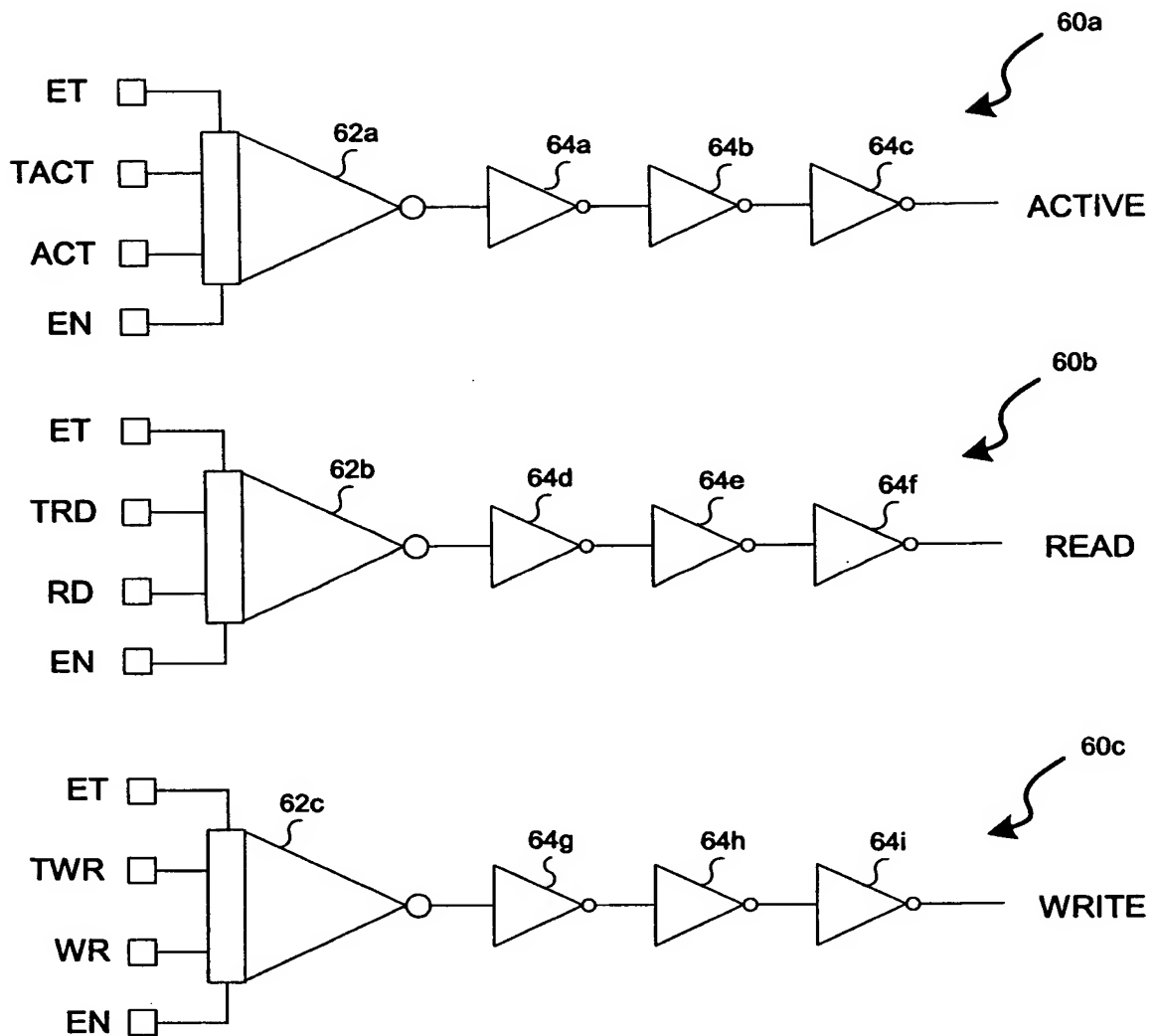


FIG. 7

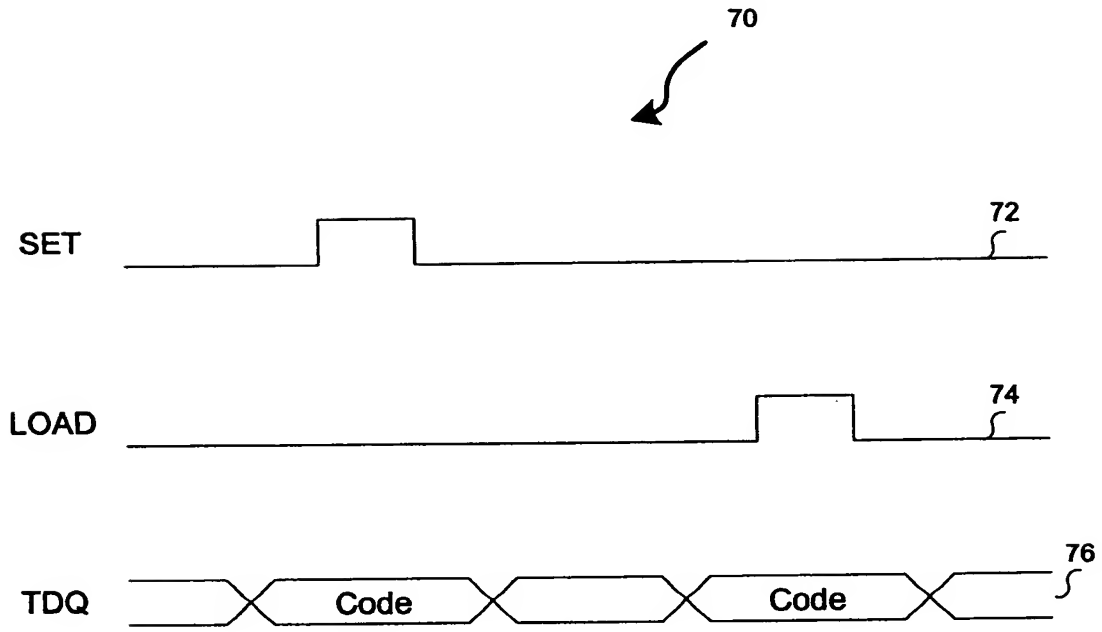
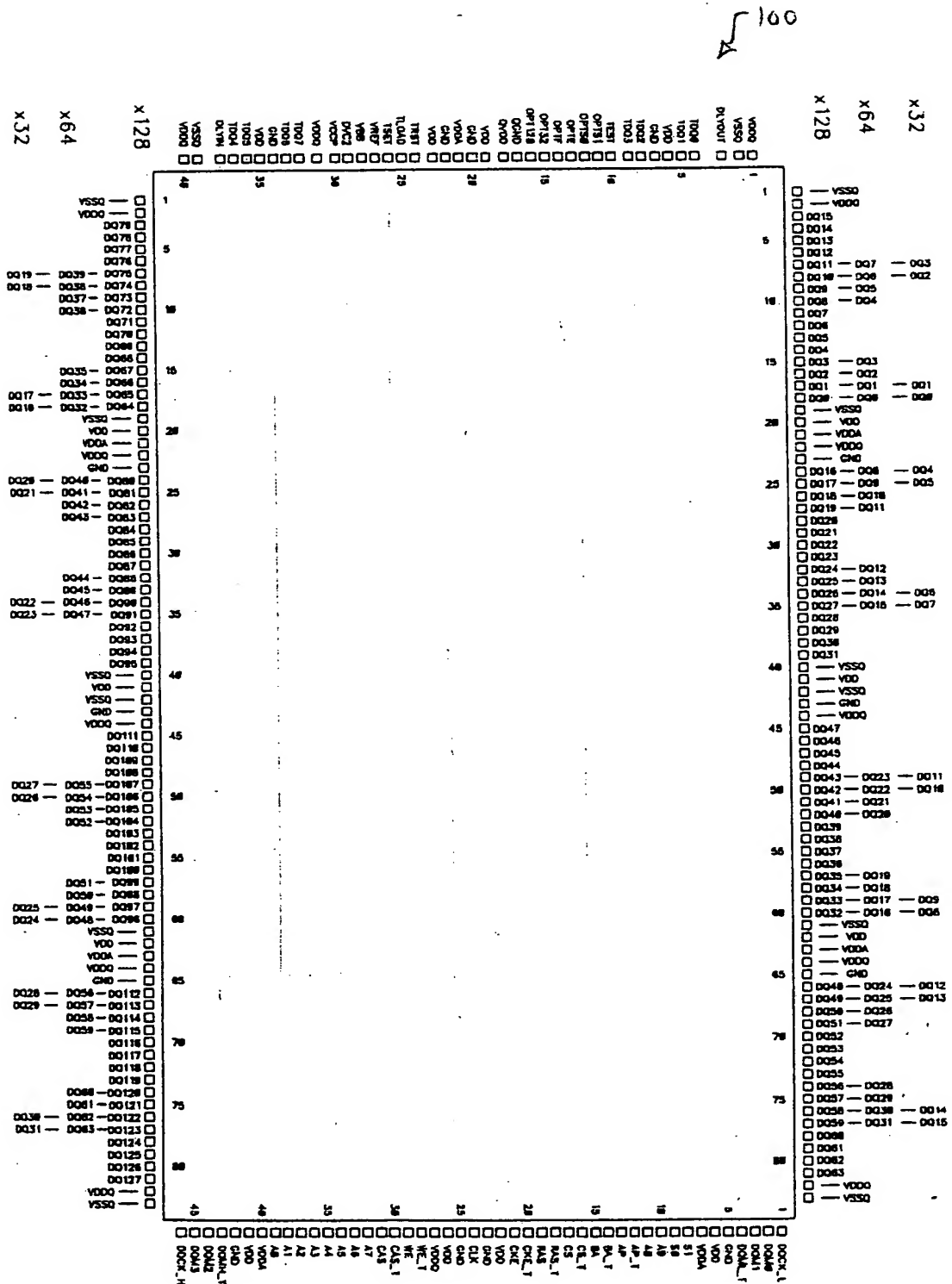


FIG. 8

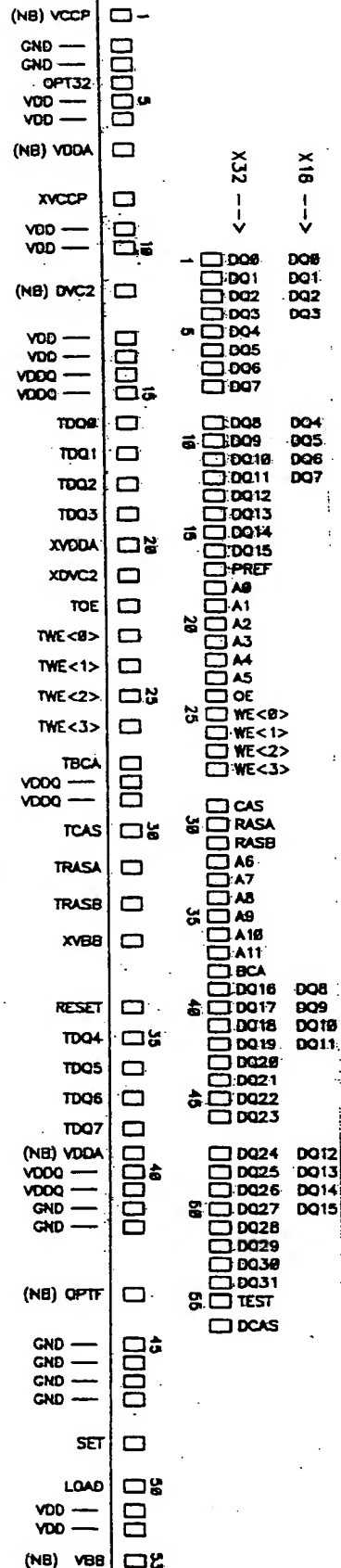


"Bonding Pads For Testing Of A Semiconductor Device"

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FIG. 9B



200

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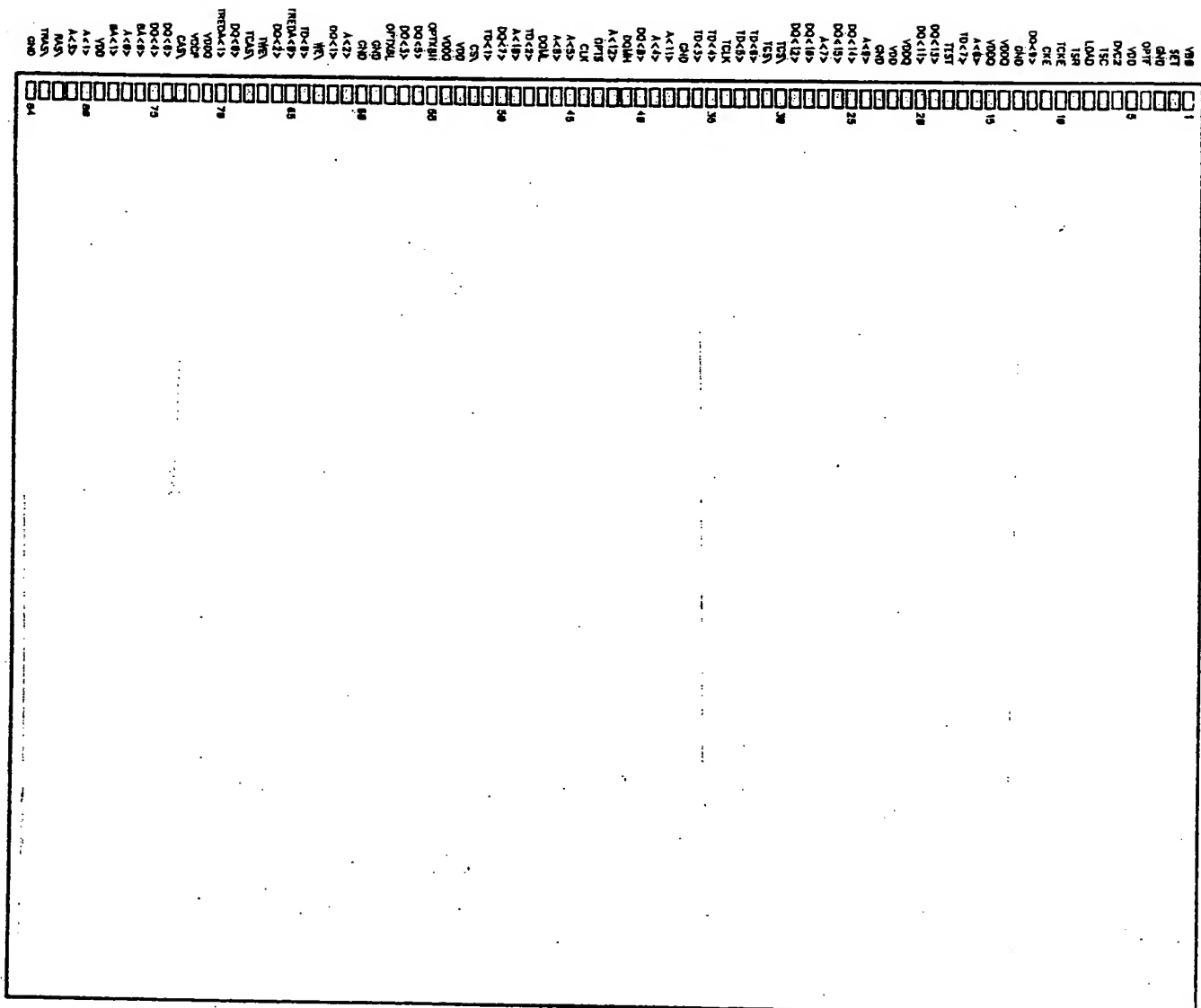


FIG. 9C

300

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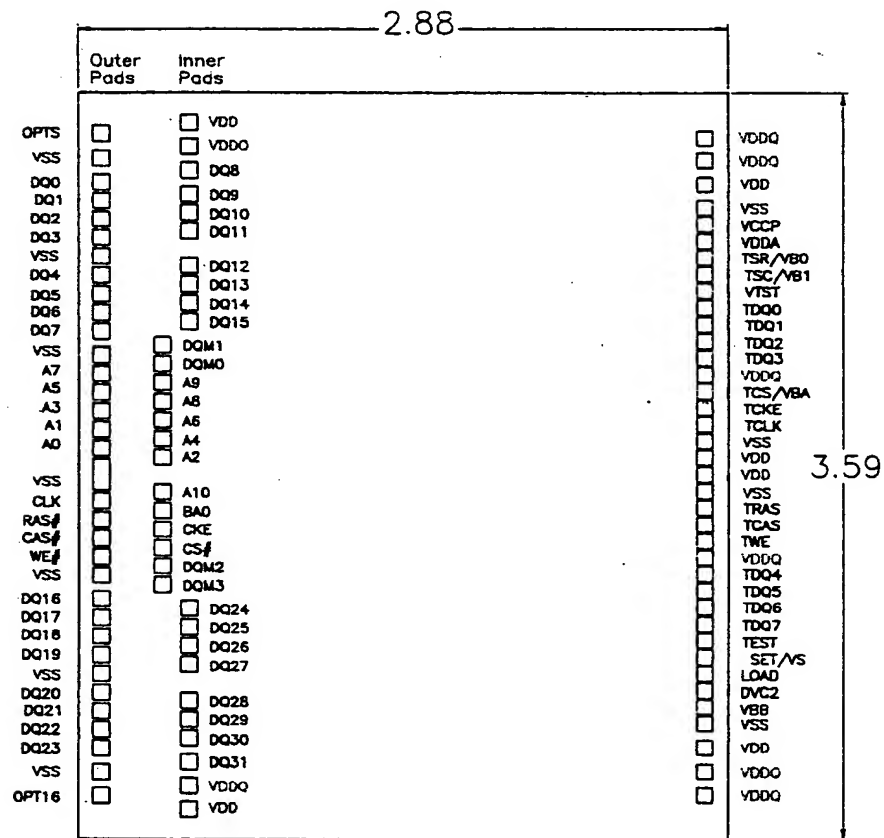


FIG. 9D

400

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Outer Pads
Inner Pads

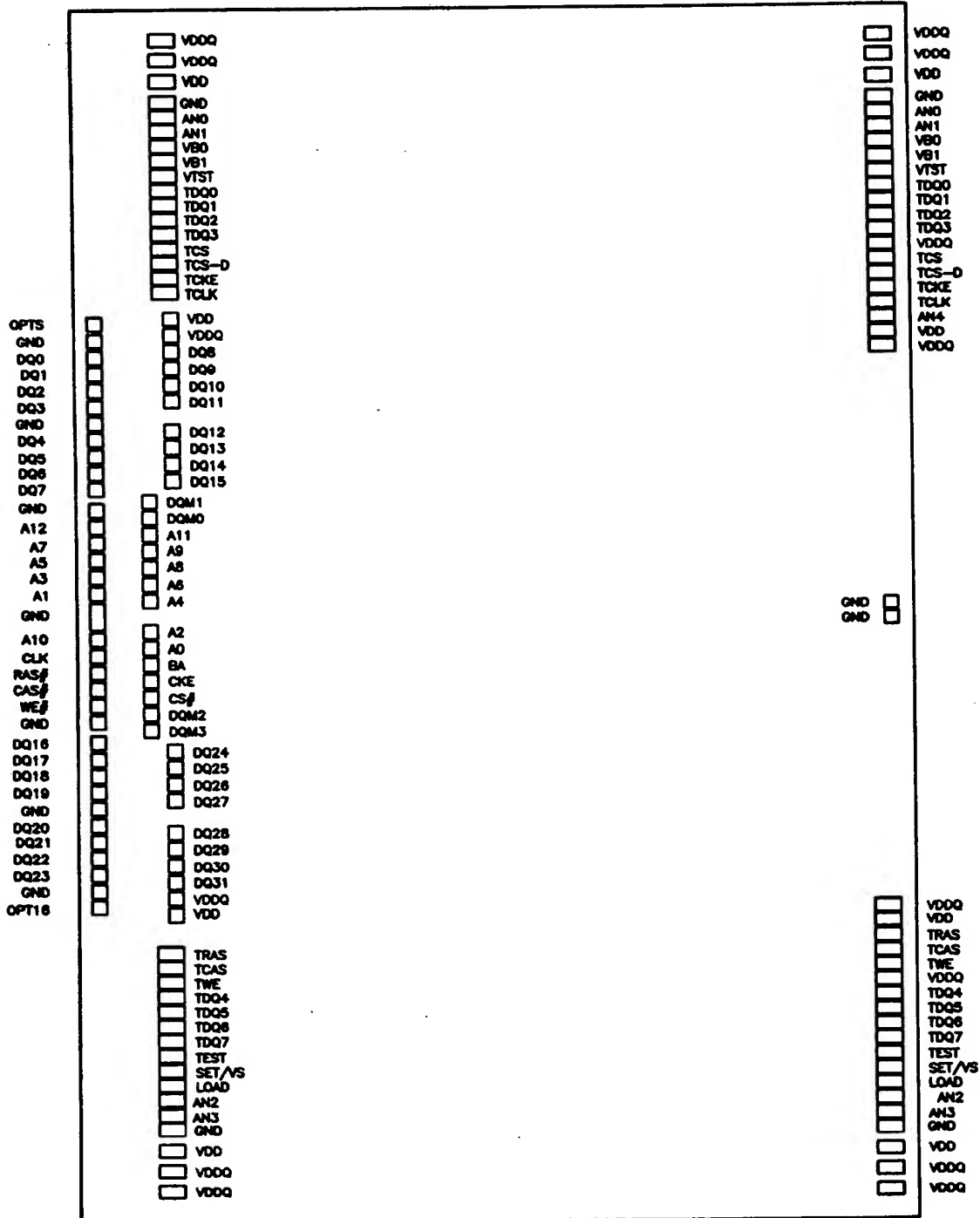


FIG. 9E